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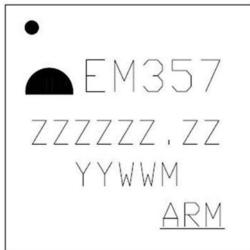
PCN Date: 4/16/2013		Effective Date: 7/19	9/2013			
Title: Add assembly site for EM357 / EM351						
Originator: KF Lee	Phor	ne: 65 6511 6428	Dept: SLI QA			
Customer Contact: Kathy Haggar	Phor	ne: 1-512-532-5261	Dept: Sales			
PCN Type:						
☐ Datasheet ☐ Four	ndry		Packing			
☐ Product Revision ☐ Asse	mbly		Labeling			
☐ Discontinuance ☐ Test			Other			
Last Order Date: Not Applicable.						
	PCI	N Details				
Description of Change: Silicon Laboratories is pleased to announce the successful qualification of a second assembly site, ASE Chung Li, Taiwan (ASECL), for EM357 and EM351 products. Product assembled at ASECL will have a different marking from the product assembled at the original assembly site, Stats Chippac Malaysia (SCM). Please see Appendix A for details of the marking differences. There is a slight difference in the dimensions of the package from ASECL, however packages from both assembly sites fall within the JEDEC specification for the 7x7 QFN (JEDEC ref: MO-220). See Appendix C for details. The new dimensions will be reflected in revision 1.3 of the datasheet.						
Reason for Change: The new assembly location will provide ad	dition	al capacity.				
Impact on Form, Fit, Function, Quality, Reliability: There is no impact to form, fit, function, quality or reliability of the product. The marking layout change as described in Appendix A.						
Product Identification: Part number Package EM357-RT/R 48QFN 7X7 EM351-RT/R 48QFN 7X7						
Last Date of Unchanged Product: N/A						
Qualification Samples: Assembled samples are available upon req Representative. A list of Silicon Labs Sales						



Customer Early Accep	tance Sign Off:
Customers may appro	ve early PCN acceptance by completing the information below:
Early Acceptance:	Date:
	Name:
	Company:
Email your early Acce	ptance approval to: <u>katherine.haggar@silabs.com</u>
Qualification Data:	
Please see Appendix B	

Embed File(s): Appendix A

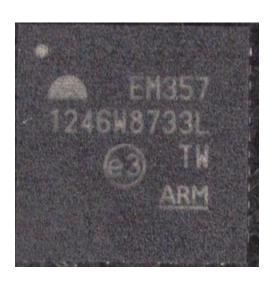
Sample Marking Layout for STATS Chippac Malaysia





Sample Marking Layout for ASE Chung Li (ASECL) $\,$







Appendix B

EM35X Qualification Report, ASECL Assembly

W7101F1 Product Qualification Plan and Report Rev. E

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Part Rev B, T	art Rev B, TSMC Fabrication, ASECL Assembly except as noted						
			Lot ID or	Fail/Pass or			
Test Name	Test Condition	Qualification	Start	End	Notes	Summary	Status
Test Group A - A	ccelerated Environment Stress	Tests					
HAST	JA110		Q33675	0/25	1		
	130°C, 85%RH	3 lots, N=>25	Q33674	0/25		3 lots	Pass
	Vcc=3.6V, 96 hours		Q33667	0/25		0/75	
	JA104		Q33669	0/25	1		
Tanan Carala	Cond C: -65°C to 150°C	3 lots, N=>25	Q33668	0/25		4 lots	Pass
Temp Cycle	500 cycles		Q33667	0/25			
			Q33677	0/77		0/152	
uHAST	JA118		Q33666	0/25	1		
	130°C, 85%RH	3 lots, N=>25	Q33665	0/25		3 lots	Pass
	96 hours		Q33670	0/25		0/75	
HTSL	JA103		Q33672	0/25	1		
	150°C, 1000hr	3 lots, N=>25	Q33671	0/25		4 lots	Pass
			Q33678	0/25			
			Q33670	0/25		0/100	

Notes:

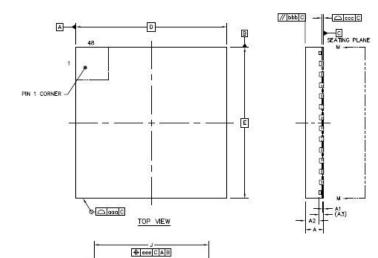
1. Parts are Pre-conditioned at MSL2/260°C

I his report applies to the following part numbers:
EM357-RT
EM351-RT

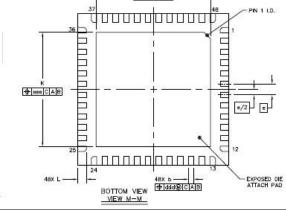
Appendix C

Package type	SCM 48QFN 7x7			ASECL 48QFN 7x7		
Dimensions	Minimum (mm)	Maximum (mm)	Nominal (mm)	Minimum (mm)	Maximum (mm)	Nominal (mm)
Package thickness	0.80	1.00	0.90	0.80	0.90	0.85
Lead Length	0.40	0.60	0.50	0.35	0.45	0.40

POD for ASECL 48QFN 7x7

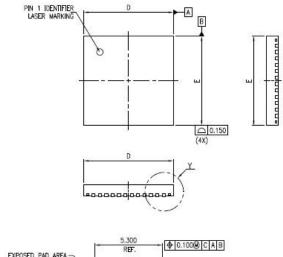


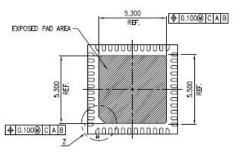
8		SYMBOL	MIN	NOM	MAX	
TOTAL THICKNESS	8	A	0.8	0.85	0.9	
STAND OFF		A1	0	0.035	0.05	
MOLD THICKNESS		A2		0.65	0.67	
L/F THICKNESS	- V	A.3	0.203 REF			
LEAD WIDTH		Þ	0.2 0.25		0.3	
DODY CITE	X	D.	7 BSC			
BODY SIZE	Y	E	7 BSC			
LEAD PITCH		e	0.5 BSC			
EP SIZE	X	J	5.2	5.3	5.4	
D- SIZE	Y	K	5.2	5.3	5.4	
LEAD LENGTH		L	0.35	0.4	0.45	
PACKAGE EDGE T	OLERANCE	000	0.1			
MOLD FLATNESS		ppp	0.1			
COPLANARITY	- 1	ccc	0.08			
LEAD OFFSET		ddd	0.1			
EXPOSED PAD OFFSET		eee	0.1			
		-0.0000				
3			8 - 8	- 1		
3	- 1					
8			5 3			

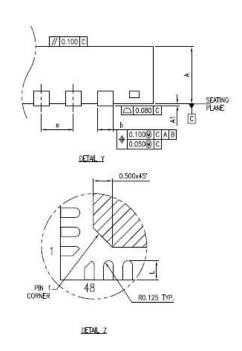


COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.

POD for SCM 48QFN 7x7







DIMENSION LIST (FOOTPRINT: 1.00)

	S/N	SYM	DIMENSIONS	REMARKS	
	-1	A	0.900±0.10	OVERALL HEIGHT	
B	2	A1	0.020 +0.050	STANDOFF	
	3	D	7.000±0.100	PKG. LENGTH	
	4	E	7.000±0.100	PKG. WIDTH	
	5	L	0.500±0.100	FOOT LENGTH	
	6	b	0.250±0.050	LEAD WIDTH	
	7	0	0.500 BASE	LEAD PITCH	7

NOTES :

S/N	DESC	DESCRIPTION			
1	GENERAL TOLERANCE.	DISTANCE	±0.100		
	ANGLE	±2.5°			
2	MATTE FINISH ON PACK EXCEPT EJECTION AND		Ra 0.3~1.2 um		
3	FRAME BASE METAL THI	0.203 BASE			
4	ALL MOLDED BODY SHA UNLESS OTHERWISE SPE	MAX. R0.200			
5	DRAWING DOES NOT INC OR CUTTING BURR.	CLUDE PLASTIC OR ME	TAL PROTRUSION		
6	COMPLIANT TO JEDEC S	TANDARD: NO220			